DOC-0368-050, REV A

MCU PROJECT BOARD - 2

Prototyping Board with Microcontroller Interface

Axiom Manufacturing • 2813 Industrial Lane • Garland, TX 75041
Email: Sales@axman.com Web: http://www.axman.com

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FIGURES

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REVISION

Date	Rev	Comments
June 15, 2005	A	Initial Release.

CAUTIONARY NOTES

Electrostatic Discharge (ESD) prevention measures should be used when handling this product. ESD damage is not a warranty repair item.

Axiom Manufacturing does not assume any liability arising out of the application or use of any product or circuit described herein; neither does it convey any license under patent rights or the rights of others.

3) EMC Information on the MCU PROJECT BOARD - 2:

This product as shipped from the factory with associated power supplies and cables, has been verified to meet with requirements of CE and the FCC as a CLASS A product.

This product is designed and intended for use as a development platform for hardware or software in an educational or professional laboratory.

In a domestic environment, this product may cause radio interference in which case the user may be required to take adequate prevention measures.

Attaching additional wiring to this product or modifying the products operation from the factory default as shipped may effect its performance and cause interference with nearby electronic equipment. If such interference is detected, suitable mitigating measures should be taken.

TERMINOLOGY

This prototyping module uses option selection jumpers to setup configuration. Terminology for use of the option jumpers is as follows:

Jumper – a plastic shunt that connects 2 terminals electrically

Jumper on, in, or installed - jumper is installed such that 2 pins are connected together

Jumper off, out, or idle - jumper is installed on 1 pin only. It is recommended that jumpers be idled by installing on 1 pin so it will not be lost.

FEATURES

The MCU Project Board – 2 is a full-featured prototyping platform intended for interfacing and programming Freescale MCU development modules in a educational environment. A line of HC(S)12(X), HC(S)08, DSP, and ColdFire modules plug directly into the project board. Other MCU boards can be interfaced directly to the project board by ribbon cable. The MCU Project Board – 2 may also be used as an electronic circuit prototyping environment without MCU support. The project board has been specifically designed for compatibility with the National Instruments Educational Laboratory Virtual Instrumentation Suite (NI-ELVIS). An integrated USB BDM has been provided to allow the user to program, erase, and debug Freescale MCU modules. Features include:

- Large, Solderless Breadboard Area
- Integrated HC(S)12(X)/HCS08 Multilink BDM
  - Allows debugging target processor via background debug mode
  - Provides all necessary signals to target processor
  - USB port connection
- 60-pin MCU Interface Connector, break-out on both ends of prototype area
- PCI Style Card-Edge connector designed for use with National Instrument's NI-ELVIS platform
- Signal Breakout arranged logically around Breadboard Area
- Power Input from included wall-plug transformer, integrated USB-BDM, or from NI-ELVIS workstation
- On-board voltage regulators provide 4 different voltage levels
  - 5VDC @ 500mA
  - 3.3VDC @ 500mA
  - +15VDC @ 50mA
  - –15VDC @ 50mA
  - NOTE: ± 15V not available when powered from USB-BDM
- LED indicators for each voltage level
- User selectable voltage to on-board logic devices
  - Option jumper to enable voltage output to MCU Port Connector
- 2 Banana Connectors
- 1 BNC Connector
- 8-pin Keypad connector
- 1 Single-turn User Potentiometer
  - Connected to MCU_PORT connector w/ separate enable
- LCD Module interface with Serial to Parallel Shift Register, w/ enable
  - Connected to MCU_PORT connector
  - Configured to mount an 8-character x 2-line LCD panel
- COM Port
  - 9-pin DSUB connector
  - RS-232 Interface with option to isolate transceiver
  - COM_SEL jumper selects configuration between:
    - RS-232 signals to transceiver
    - MON08 Interface Port
  - Access to COM signals at Signal Breakout Connector
- Socket for Optional Crystal Oscillator
  - User selectable output amplitude - 5V or 3.3V
- 8 Active-High Green LED's, Buffered, with enable
  - 4 LED's connected to MCU_PORT connector w/ separate enable
- 8 Active-Low Push Button Switches
  - 4 Push Button Switches connected to MCU_PORT connector w/ separate enable

- 8 Active-High DIP Switches,
- 1 External-drive Buzzer
  - Connected to MCU_PORT connector w/ separate enable
- Mounting hole placement allows the student to carry the Project Board in a standard 3-Ring binder.

Specifications:

Module Size:	8.5” x 11”
Power Input:	+9V @ 1.2A typical

REFERENCES

Reference documents are provided on the support CD in Acrobat Reader format. Further information, including project examples, can be found on the Axiom Manufacturing web site at www.axman.com.

MCUPB2_SCH_A.pdf	MCU Project Board – 2 Schematic, Rev A
MCUPB2_UG.pdf	MCU Project Board – 2 User Guide (this document)
CSM12C32_UG.pdf	CSM-12C32 User Guide
CSM12C32_SCH_B.pdf	CSM-12C32 Schematic, Rev B

GETTING STARTED

To get started quickly, please refer to the Getting Started with the Microcontroller Student Learning Kit included on the Support CD. The quick start will show the user how to configure the board for use with the CSM12C32 module. The quick start will also show the user how to install the latest version of Metrowerks’ CodeWarrior software tools and how to create and build and debug a simple application.

NOTE: Install the CodeWarrior Development Studio tools and all applicable patches before attempting to connect the MCU Project Board – 2 to a host PC.

OPERATION

The MCU Project Board – 2 allows users to quickly and easily prototype electronic circuits with, or without, MCU support. It provides a variety of commonly used circuits pre-installed and ready for use. Dual-row header sockets placed around the prototyping area provide convenient access to all on-board features. Connections between these signals and the breadboard are made using solid, 22ga, jumper wire connected to the proper socket header location. A package of jumper wires is included with the project board. The sections below describe, in detail, the functionality of the MCU Project Board – 2.

Power

The MCU Project Board – 2 may be used as a stand-alone prototyping platform or in conjunction with the NI-ELVIS platform. The project board will accept power input from the included wall-plug transformer or from the NI-ELVIS workstation. The project board may also be powered from the integrated USB BDM.

CAUTION: Exercise care when configuring power input and output selections to prevent damage to the project board or connected circuitry.

Input Sources

The MCU Project Board – 2 provides the user 4 discrete working voltage levels: 5V, 3.3V, +15V, and -15V. The 5V and the ±15V rails have multiple input sources while the 3.3V rail is derived from the 5V rail in all configurations. Option headers JP1 (P_SELA), JP2 (PSEL_B), and JP3 (VDD_SEL) configure power routing on the project board. See the Input Selection section below for details on setting up power configuration for the project board.

The 5V rail is driven from one of three input sources. In stand-alone operation, the 5V rail may be supplied by the on-board voltage regulator, the integrated BDM, or the NI-ELVIS workstation. A barrel connector input at VIN accepts a 2.1mm, center-positive, barrel plug, allowing power to be supplied by a transformer or desktop power supply. Input voltage on VIN must be kept between +8V and +12V for proper operation. Typical input is +9V. Although VR1 will accept inputs to 20V, increasing the input voltage will increase the voltage drop across the part. This may lead to excessive temperatures causing the part to shut down.

The 5V rail is derived from the on-board voltage regulator at VR1. VR1 supplies a maximum of 1A of current to the project board. The regulator features over-current and over-temperature protection. The regulator will automatically shut down if current or temperature exceeds rated specifications.

The integrated BDM drives the 5V rail directly from the USB bus. Note that when powering the project board from the integrated USB BDM, **total** current drain must not exceed **500mA**. Total current drain includes the BDM circuit, all enabled project board circuitry, any attached MCU module, and any additional prototype circuitry connected to the project board. Excessive current drain will violate the USB specification and will cause the USB bus to shutdown.

When attached to the NI-ELVIS workstation, the 5V rail is driven through connector J1 from the workstation. Refer to the NI-ELVIS workstation user manual for further details.

The 3.3V rail is supplied from an on-board regulator located at VR2. The VR2 input is connected to the 5V input through selection header PSEL_B. VR2 supplies a maximum of 500mA of current to the project board. The 3.3V regulator also features over-current and over-temperature protection.

The ±15V rails are supplied from either an on-board boost regulator at PS1 or the NI-ELVIS workstation through connector J1. The PS1 input is derived from VIN connector through the regulator at VR1. If powered from VIN and an external power supply, current on the ±15V rails is limited to 50 mA. In this configuration, PS1 will consume 500mA of current output from VR1. If powered from the NI-ELVIS workstation, the ± 15V rails are provided directly from the workstation. The workstation will provide a maximum current on the ±15V rails of 500 mA. The PS1 voltages and the J1 voltages are diode OR'ed to prevent component damage.

Total current available is dependent on the configuration chosen and the load placed on each voltage rail. For instance, consider the following setup. The project board is powered from a transformer connected to VIN. A 50mA load is placed on the +15V and the –15V rails for the analog portion of the circuit. Additionally, a 500mA load is placed on the 3.3V rail. In this configuration, any load placed on the 5V rail will cause an over-current condition in regulator VR1.

The table below lists current limits for each voltage rail in different input configurations. Each current limit shows the maximum provided except in the case of the USB input. The USB input assumes the USB circuitry consumes 200mA of peak current. It is the users responsibility to ensure current limits are not exceeded in any configuration.

Table 1: Current Limits

POWER LIMITS	USB	5V, 300mA
		3.3V, 200mA
		N/A
	VIN	5V, 500mA
		3.3V, 500mA
		±15V, 50mA
	J1	5V, 500mA
		3.3V, 500mA
		±15V, 500mA
		±12V, 500mA

Total current drain from USB bus **must not** exceed 500 mA. Excessive current drain will violate the USB specification.

NOTE: 3.3V rail is derived from 5V rail for all inputs. Total current available on 3.3V rail is limited by total current available on 5V rail.

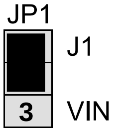
Input Selection

The MCU Project Board – 2 sources power from the VIN barrel connector, the USB BDM, or connector J1. The barrel connector is situated on the project board to prevent connection of an external power supply while connected to the NI-ELVIS workstation. Two selection headers determine the source of input power to the project board. These selection headers are situated to prevent selecting 2 input power sources at the same time.

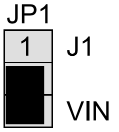
Selection headers PSEL_A (JP1) and PSEL_B (JP2) determine which input source is selected to supply power to the project board. PSEL_A selects either connector VIN or connector J1 as an input source. PSEL_B selects either the output of PSEL_A or the USB BDM as an input source. The output of PSEL_A connects directly to pin 3 of PSEL_B. The output of PSEL_B drives the 5V rail and the input of the 3.3V regulator, VR2.

Figure 1: Input Power Select – JP1, JP2

PSEL_A



Selects J1 input source

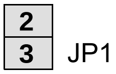


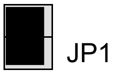
Selects VIN input source

PSEL_B

Selects USB input source to supply 5V rail

Selects JP1 input source to supply 5V rail.





Power input on the barrel connector is supplied by the included wall-plug transformer or a desktop power supply. Input voltage on this connector should be between +8V and +12V. Higher input voltages may cause excessive heating and force VR1 into thermal shutdown.

Power input from the USB connector is drawn from the USB bus. Care must be exercised not to draw too much power when connected to the USB bus. USB2.0 specifications limit the total current drain from the bus to less than 500mA. Exceeding this limit will cause the USB device to disconnect and may damage the project board or host PC.

VDD Selection

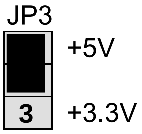
The operating voltage level VDD supplies all on-board logic devices on the MCU Project Board – 2. An option header allows the user to set VDD at either 5V or 3.3V.

When the project board is connected to a wall-plug transformer, voltage regulator VR1 provides the 5V rail and regulator VR2 provides the 3.3V rail. Regulator VR1 is rated for a maximum current output of 1A while regulator VR2 is rated for a maximum current output of 500mA. In this configuration, ±15V is provided by the regulator at PS1. Both PS1 and VR2 derive their input from VR1. This setup may limit available current in mixed voltage applications. Each regulator is internally current limited to prevent damage from inadvertent, short circuits of **short duration**. The regulator at PS1 is not protected from continuous short-circuits on its output.

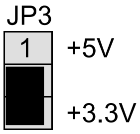
When connected to NI-ELVIS, the 5V rail is provided by the workstation. This input also drives the 3.3V regulator at VR2. ±15V is available from the workstation and PS1 is not connected.

A 3-pin option header, JP3, VDD_SEL, allows the user to select the operating voltage routed to VDD. The 5V selection routes 5VDC to on-board logic while the 3.3V selection routes 3.3VDC to on-board logic. All voltage levels are conveniently arranged around the prototype area to allowing easy access. ±15V voltage inputs are diode OR'ed and available at connector J4.

Figure 2: VDD _SEL Option Header – JP3



Sets VDD to +5v



Sets VDD to +3.3V

CAUTION: Exercise care to select the correct operating voltage when interfacing to on-board logic to prevent damaging circuit elements.

±15V Power

The MCU Project Board – 2 includes a DC-DC converter at PS1 to supply ±15V for use in analog circuit construction and analysis. PS1 provides a maximum of 50mA on each output.

PS1 draws its input from the +5V rail. An option header at JP11 disables PS1 if not needed. Disabling PS1 when not used conserves power and will prolong the life of the +5V LDO at VR1.

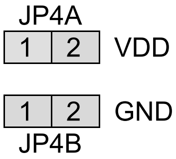
Table 2: PS1_EN Option Header – JP11

Shunt	Effect
ON	Enables PS1 output to the project board
OFF	Disables PS1 output to the project board

MCU Module Power

The MCU Project Board - 2 may optionally power modules attached to the MCU_PORT connector. Two, 2-pin headers at JP4A and JP4B enable or disable power to the MCU_PORT. Installing shunts at positions labeled VDD and GND connects MCU_PORT, pin 1 to VDD on the project board and MCU_PORT, pin 3 to GND on the project board. Note that to complete the circuit, both shunts must be installed. If not used, both shunts should be removed.

Figure 3: MCU_MOD_PWR Option Header – JP4



Placing a shunt on JP4A routes VDD to MCU_PORT-1.

Placing a shunt on JP4B routes GDN to MCU_PORT-3

CAUTION: When using this option selections make sure the module connected to the MCU_PORT is not configured to source voltage to the project board. Damage to both the project board and attached module may result.

Integrated BDM

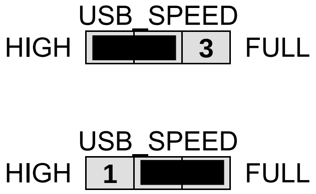
The MCU Project Board – 2 board features an integrated USB BDM from P&E Microcomputer Systems. The integrated BDM supports application development and debugging via background debug mode. All necessary signals are provided by the integrated BDM. A USB, type B, connector provides connection from the target board to the host PC. Communication and control signals (BGND, RESET*) are connected directly to the MCU_PORT. This arrangement allows the user to program and debug a line of MCU modules from Axiom Manufacturing directly without additional cabling.

The integrated USB BDM provides 5V power and ground to target board eliminating the need to power the board externally. Power provide by the integrated BDM is derived from the USB bus. Total current consumption for the project board, and connected circuitry, must not exceed **500mA**. This is the current supplied by the USB cable to the BDM, target board, and any connected circuitry. Excessive current drain will violate the USB specification causing the USB bus to shutdown.

USB Speed

The communications speed over the USB bus is controlled by the USB_SPEED header. When shipped from the factory, the board is configured for high-speed operation. If the user encounters a communication failure, or erratic behavior, USB communication speed may be reduced by setting this option jumper to Full. Slowing the communications rate often resolves any problem encountered.

Figure 4: USB_SPEED Option Header



Configuration:
Selects USB High-speed communications

Selects USB Full-speed communications

CAUTION: Do not allow total current drain to exceed 500mA when powered from the USB BDM.

BDM Voltage

The integrated BDM is designed to interface with either 5V or 3.3V circuits. The VDD level selected on the MCU Project Board – 2 is fed back to the BDM to set output drive levels. The VDD level is selected by JP3 (VDD_SEL) option header. Further details on operating voltage selection may be found in the POWER section above.

As noted above, **total** current drain from the integrated BDM must not exceed **500mA.** Excessive current drain will violate the USB 2.0 specification causing the USB bus to shutdown.

User I/O

The MCU Project Board - 2 provides an array of User I/O to allow connection of auxiliary components such as signal input, test equipment, Keypads, or LCD displays.

LCD PORT

The MCU Project Board - 2 includes a LCD port with supporting shift register logic to allow the user to easily add a LCD display. Two output connectors provide support for various LCD panel cables. A 2x7 pin header supports most cable configurations while a 1x14 auxiliary pin header provides an alternate connection. The 1x14 pin header is not installed in default configuration. This interface supports displays with up to 80 characters in 4-bit bus mode. The LCD module VEE or contrast potential is set 0 Volts on this board. This configuration requires a TN style (Standard Twist) and Reflective LCD module such as the Axiom Manufacturing, HC-LCD. The LCD Module is configured for Write only mode. It is not possible to read current cursor position or the busy status back from the module

LCD Port Connectors

The LCD_PORT interface is connected directly to the MCU_PORT I/O headers. The signal arrangement is designed to coincide with the SPI port of a line of plug-in modules designed by Axiom Manufacturing. To provide maximum flexibility, the select signal SS* has been connected to both a dedicated SS* output and to a GPIO signal on the MCU module. This allows the use of multiple SPI ports if needed. An option header at JP5, SS*, selects the select signal source. To prevent signal corruption when using these signals as general purpose I/O, the user must disable HC595 shift register (U5) by removing the SS* jumper.

Figure 5: LCD Connector – J8

5V	**2**	**1**	GND
RS	**4**	**3**	CONSTRAST
EN	**6**	**5**	R/W*
DB1	**8**	**7**	DB0
DB3	**10**	**9**	DB2
LCD_D5	**12**	**11**	LCD_D4
LCD_D7	**14**	**13**	LCD_D6

SPI data bit definitions to LCD Port:
LCD_D[7..4] – LCD data bits D[3..0]
DB[3..0] – Unused, 10K ohm pull-downs installed
R/W – Read/Write pin, set to 0 volts, Read only
EN – LCD enable input, 1 = LCD enable
CONTRAST – LCD contrast input
RS – Register Select, 0 = LCD Command, 1 = LCD Data

The AUX_LCD connector provides an alternate LCD panel connection. This connector is not installed in default configuration. The same feature set applies to this connection as applies to the dual-row connector.

Figure 6: AUX_LCD Connector – J9

GND	**1**
5V	**2**
CONTRAST	**3**
RS	**4**
R/W*	**5**
EN	**6**
DB0	**7**
DB1	**8**
DB2	**9**
DB3	**10**
LCD_D4	**11**
LCD_D5	**12**
LCD_D6	**13**
LCD_D7	**14**

SPI data bit definitions to LCD Port:
LCD_D[7..4] – LCD data bits D[3..0]
DB[3..0] – Unused, 10K ohm pull-downs installed
R/W – Read/Write pin, set to 0 volts, Read only
EN – LCD enable input, 1 = LCD enable
CONTRAST – LCD contrast input
RS – Register Select, 0 = LCD Command, 1 = LCD Data

The LCD8_2 connector supports mounting an 8-character x 2-line LCD panel directly to the project board. This connector is pinned-out to mate directly to the Optrex DMC-50448N LCD module. This connector is not populated in default configuration. The same feature set applies to this connection as applies to the dual-row connector.

Figure 7: LCD8_2 Connector – J13

GND	**1**	**2**	VDD
CONTRAST	**3**	**4**	RS
R/W*	**5**	**6**	EN
DB0	**7**	**8**	DB1
DB2	**9**	**10**	DB3

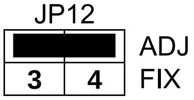
SPI data bit definitions to LCD Port:
LCD_D[7..4] – LCD data bits D[3..0]
DB[3..0] – Unused, 10K ohm pull-downs installed
R/W – Read/Write pin, set to 0 volts, Read only
EN – LCD enable input, 1 = LCD enable
CONTRAST – LCD contrast input
RS – Register Select, 0 = LCD Command, 1 = LCD Data

LCD_D4	**11**	**12**	LCD_D5
LCD_D6	**13**	**14**	LCD_D7

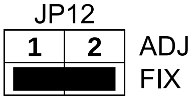
LCD Contrast

The MCU project board offers two methods for controlling the LCD panel contrast – Fixed or Adjustable. The fixed option provides near maximum contrast and supports all TN type LCD panel such as the Axiom Manufacturing, HC-LCD. The adjustable option allows the use on the on-board POT to vary the contrast voltage applied to the LCD panel. This allows the user to apply temperature or lighting compensation if needed.

Figure 8: Contrast Select – JP12



Selects on-board POT to allow adjustment of LCD contrast voltage.



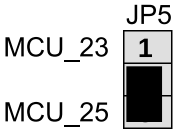
Selects fixed LCD contrast voltage.

LCD Select

To allow maximum flexibility, the control signal used to transfer data to the LCD panel is selectable. Option header SS* (JP5) selects between the SPI port SS* signal or the GPIO signal connected to MCU_PORT-25.

Figure 9: SS* Option Header – JP5

Selects dedicated SS input source



Selects GPIO signal on MCU_25

NOTE: To prevent signal corruption when using the SPI signals as GPIO, the user should idle the SPI circuitry by removing the SS* jumper.

Oscillator Socket

The MCU Project Board - 2 provides a socket for an optional Clock Oscillator. The socket is configured to accept either 14-pin oscillator or 8-pin canned crystal oscillators. An OSC_OPT option jumper allows the use of 5V oscillators to drive 3.3V circuits. Removing the option jumper routes the clock output through a simple voltage divider thereby reducing the output amplitude. Installing the option jumper allows a 5V, peak, clock output. This output is routed to the signal breakout header located adjacent to the breadboard.

Table 3: OSC_OPT Option Header – JP7

Shunt	Effect
ON	Oscillator Output at Full Amplitude – $5V_{PP}$
OFF	Oscillator Output at Reduced Amplitude – $3.3V_{PP}$

Switches

The MCU Project Board - 2 provides two types of switches for use as input devices. Eight normally open push button switches and eight normally open DIP Switches arranged in two banks of four switches each. All switches are biased to provide a known voltage level while in the inactive state.

PUSHBUTTON SWITCHES

Each push button switch is configured for active-low operation. When pressed (closed) the associated signal line is pulled to GND through a 1 kΩ, current-limit resistor. A 10k ohm resistor pulls each signal line to VDD when the switch is released (open). Each push-button switch output is routed to the signal breakout header located adjacent to the breadboard. Four push-button switches are connected directly to the MCU_PORT connector. See Connected Features section below for details.

DIP SWITCHES

Each DIP switch is configured for active-high operation. When ON (closed), each switch leg is individually pulled to VDD through a 100 Ω series, current limit resistor. A 10k ohm resistor pulls each signal line to GND when the switch is OFF (open). Each DIP switch output is routed to the signal breakout header located adjacent to the breadboard.

LED's

The MCU Project Board - 2 provides 8, green, LED's, for use as output indicators. Each LED is configured for active-high operation. Each LED is individually driven by an ACT buffer allowing either 5V or 3.3V input levels. The input level is determined by VDD selection. A 10K ohm resistor holds each buffer input low to prevent inadvertent LED activation. The LED buffer driver may be disabled by removing the shunt at LED_EN. LED inputs are routed to the signal breakout header located adjacent to the breadboard. Four LED's are connected directly to the MCU_PORT connector. See Connected Features section below for details.

Table 4: LED_EN Option Header – JP6

Shunt	Effect
ON	Enable LED Output
OFF	Disable LED Output

Keypad

The KEYPAD connector supports connection of a passive 12-key or 16-key keypad. The KEYPAD connector is routed directly to the signal breakout located adjacent to the breadboard. No current-limit is provided on this connection and should be provided by the user if required.

Figure 10: Keypad Connector – J12

KEYPAD 8	8
KEYPAD 7	7
KEYPAD 6	6
KEYPAD 5	5
KEYPAD 4	4
KEYPAD 3	3
KEYPAD 2	2
KEYPAD 1	1

These signal connect directly to the User I/O signal breakout connector located below the breadboard.

Potentiometer

The MCU Project Board - 2 provides a single-turn, 5K ohm trim potentiometer for use in circuit prototyping. The POT may be used to analog input signals. This signal is routed to the signal breakout header located adjacent to the breadboard. A bypass capacitor on the output provides minimal smoothing on the POT signal.

The POT is configured as a Connected Feature. See Connected Features section below for details.

Banana Jack

The MCU Project Board - 2 provides two 4.0mm Banana jacks for use as auxiliary I/O. These connectors may be used for auxiliary signal input or for signal output to test equipment. The Banana jacks are color-coded, red, and black. The center conductor of each jack is routed to the User I/O Signal Breakout connector located adjacent to the breadboard area.

BNC Jack

The MCU Project Board - 2 provides one BNC jack for use as auxiliary I/O. This connector may be used for auxiliary signal input or for signal output to test equipment. The center conductor (BNC+) and shield (BNC-) are routed separately to the User I/O Signal Breakout connector located adjacent to the breadboard area. For proper operation, both signals must be connected. For most circuit configurations, BNC- should be connected to GND.

Connected Features

To simplify circuit construction and emphasize software development, several user features have been connected to the MCU_PORT through FET switches. The FET switches are controlled by enable signals that are also routed to the MCU_PORT header. This setup allows the user to electronically connect and disconnect each connected feature group. A 6-position jumper allows the user to disconnect the enable signal if applying the associated port to other uses. Connected Features include a POT, 4 push-button switches, and 4 LED's. Each feature group function is more fully described elsewhere in this User Guide.

POT

The POT signal is routed to MCU_PORT-20 through a FET switch. This feature is controlled by a GPIO port signal on MCU_PORT-32 allowing the user to enable or disable this feature under MCU control. An option header at JP10 isolates this enable signal allowing the user to apply the GPIO signal for other uses.

Table 5: POT Connections

FEATURE	CONNECTION
POT	MCU_PORT – 20
ENABLE	MCU_PORT - 32
OPTION	JP10-4 (POT)

PUSH-BUTTON SWITCHES

PB1 – PB4 are connected the MCU_PORT through a FET bus switch. This feature is controlled by a GPIO port signal connected to MCU_PORT-36 allowing the user enable or disable this feature under MCU control. An option header at JP10 isolates this enable signal allowing the user to apply the GPIO signal for other uses.

Table 6: PB Switch Connections

FEATURE	CONNECTION
PB1	MCU_PORT – 9
PB2	MCU_PORT – 11
PB3	MCU_PORT – 29
PB4	MCU_PORT – 31
ENABLE	MCU_PORT – 36
OPTION	JP10-2 (PB)

LED's

LED1 – LED4 are connected the MCU_PORT through a FET bus switch. This feature is controlled by a GPIO port signal connected to MCU_PORT-34 allowing the user enable or disable this feature under MCU control. An option header at JP10 isolates this enable signal allowing the user to apply the GPIO signal for other uses.

Table 7: LED Connections

FEATURE	CONNECTION
PB1	MCU_PORT – 33
PB2	MCU_PORT – 35
PB3	MCU_PORT – 37
PB4	MCU_PORT - 39
ENABLE	MCU_PORT - 34

OPTION	JP10-3 (LED)

Buzzer

The MCU Project Board features an external drive buzzer for audible applications. The buzzer is connected to the MCU_PORT through an option header at JP10, FEA_EN. The buzzer is connected to a TIMER or PWM port on all MCU modules currently developed. The buzzer is connected directly to the MCU _PORT connector and does not require a enable signal similar to the other Connected Features.

Feature Enable

Each Connected Feature is enabled by applying the appropriate signal level to the enable line for that feature set. Each connected feature group may be enabled or disabled independent of the other groups. **Note,** that enable signal logic levels are not the same for all feature groups. The appropriate logic level for each group is shown in the table below. Each Connected Feature is enabled as a group; i.e. all push-buttons are enabled or disabled, all LED's are enabled or disabled, the POT is enabled or disabled.

Table 8: User Feature Enable

USER FEATURE	ENABLE SIGNAL		SIGNAL LEVEL	
			ENABLE	DISABLE
Push-Buttons	PB_EN	MCU_PORT-36	0	1
LED's	LED_EN	MCU_PORT-34	0	1
POT	POT_EN	MCU_PORT-32	1	0

To prevent signal corruption, each enable signal may be isolated from the MCU_PORT. An option header at JP10 allows each enable signal to be isolated individually. This allows the GPIO port signal applied to the Connected Feature Enable to be used for other purposes.

Table 9: FEA_EN Option Header

FEA_EN				SHUNT	
				ON	OFF
BZ	1	2		ENABLE	DISABLE
PB	3	4		ENABLE	DISABLE
LED	5	6		ENABLE	DISABLE
POT	7	8		ENABLE	DISABLE

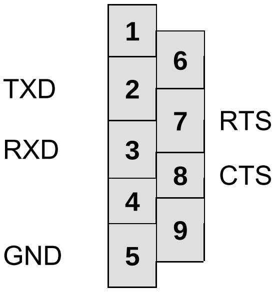
COM Port

The MCU Project Board - 2 provides a single RS-232 communications port configured as a DCE device. An RS-232 transceiver provides RS-232 signal level to TTL/CMOS logic level translation services. The RS-232 translator operates at either 3.3V or 5V.

Communication and handshake signals may be individually enabled/disabled to the transceiver by the COM_EN option header. The COM connector and transceiver supports both RS-232 and MON08 communications on the board. The COM_EN option header enables the communications protocol used.

In addition to the communications services below, each signal input from the COM connector is routed to the signal breakout connector located adjacent to the breadboard. This allows the user to implement communications protocols not built-in to the project board.

Figure 11: COM Port Connector - COM



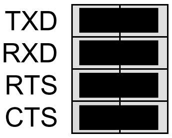
Female DB9 connector that interfaces to the DCE serial port via an RS232 transceiver. It provides simple 2-wire asynchronous serial communications without flow control. A straight-through serial cable may be used to a DTE device such a PC

Pins 1, 4, 6, and 9 are routed to the User I/O Signal Breakout connector located adjacent to the breadboard.

COM_EN Option Header

The COM_EN option header allows the user to disconnect the on-board RS-232 transceiver. This allows the user to implement alternate communications protocols such as RS422/485 with out conflict from the installed transceiver.

Figure 12: COM_EN Option Header – JP9

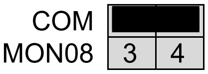


The illustration to the left shows all signals enabled.
Remove shunts to isolate each signal individually

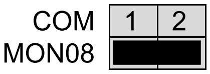
COM_SEL Option Header

The COM_SEL option header is a 12-pin header used to route the RS-232 transceiver output to the appropriate circuit. Outputs for the RS-232 and MON08 functionality are routed to the signal breakout header located adjacent to the breadboard. The BDM output is routed to the BDM pod.

Figure 13: COM_SEL Option Header – JP8



Selects RS-232 communications



Selects MON08 communications protocol

NOTE: Enabling RS-232 and MON08 communications at the same time will cause data corruption.

RS-232

Translated RS-232 signals TX and RX are available to the user at the signal breakout header located adjacent to the breadboard. Translated handshaking signals RTS and CTS are also available. The user will need to configure hand-shaking as required by the communications application used.

MON08

A single wire MON08 interface is available to the user at the signal breakout header located adjacent to the breadboard. A zener diode and resistor combination provides the high-voltage (VTST) necessary to force MON08 monitor mode. This voltage is fixed at 8.2V and may be excessive for 3.3V HC08 MCU's. It is the users responsibility to reduce the VTST voltage level if necessary. VTST is available when the board is power from either the VIN connector or from the NI-ELVIS workstation.

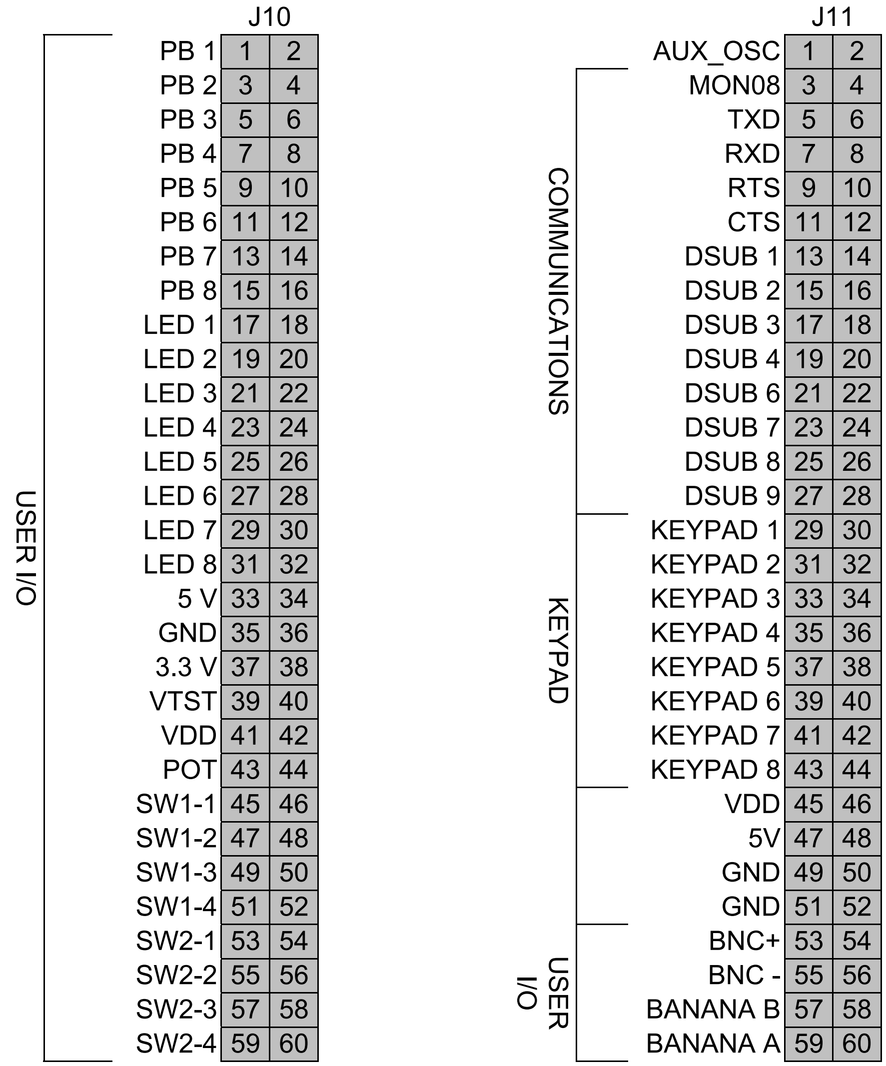
SIGNAL BREAKOUT

An important feature of the MCU Project Board - 2 is the large, centrally located, breadboard area. Dual-row socket headers strategically placed around the breadboard provide signal access to the on-board circuits. Signal breakout may be grouped into 3 broad categories: MCU Access Signals, User I/O Signals, and NI-ELVIS Signals

USER I/O

User I/O signal breakout connectors provide access to all on-board components. These connectors are located adjacent to the breadboard with signals strategically located to simplify access. Each signal and signal group is labeled to ease signal identification and location. To ease prototyping, each signal is routed to two socket locations. This allows the user to easily route each to signal to multiple locations if desired. The table below details the USER I/O Signal Breakout connectors.

Figure 14: USER I/O Signal Breakout – J10, J11



	J10	
PB 1	1	2
PB 2	3	4
PB 3	5	6
PB 4	7	8
PB 5	9	10
PB 6	11	12
PB 7	13	14
PB 8	15	16
LED 1	17	18
LED 2	19	20
LED 3	21	22
LED 4	23	24
LED 5	25	26
LED 6	27	28
LED 7	29	30
LED 8	31	32
5 V	33	34
GND	35	36
3.3 V	37	38
VTST	39	40
VDD	41	42
POT	43	44
SW1-1	45	46
SW1-2	47	48
SW1-3	49	50
SW1-4	51	52
SW2-1	53	54
SW2-2	55	56
SW2-3	57	58
SW2-4	59	60

	J11	
AUX_OSC	1	2
MON08	3	4
TXD	5	6
RXD	7	8
RTS	9	10
CTS	11	12
DSUB 1	13	14
DSUB 2	15	16
DSUB 3	17	18
DSUB 4	19	20
DSUB 6	21	22
DSUB 7	23	24
DSUB 8	25	26
DSUB 9	27	28
KEYPAD 1	29	30
KEYPAD 2	31	32
KEYPAD 3	33	34
KEYPAD 4	35	36
KEYPAD 5	37	38
KEYPAD 6	39	40
KEYPAD 7	41	42
KEYPAD 8	43	44
VDD	45	46
5V	47	48
GND	49	50
GND	51	52
BNC+	53	54
BNC -	55	56
BANANA B	57	58
BANANA A	59	60

NOTE: Signal DSUB5 is connected directly to GND.

MCU_PORT

A unique feature of the MCU Project Board - 2 is the ability to interface directly with a line of MCU Development Boards from Axiom Manufacturing. These development boards either plug directly into the MCU_PORT or connect through a ribbon cable. The signals originating at the MCU_PORT connector are routed to two sets of dual-row socket headers located at both ends of the breadboard. All MCU_PORT signals are available at both signal breakout locations. This allows the user to easily prototype circuits at either end of the breadboard. Signal placement at these breakout locations is dependent on signal orientation at the MCU_PORT. See the user manual for the specific MCU module for signal breakout.

Figure 15: MCU_PORT Signal Breakout – J5, J6, J7

	J5				J6				J7		
M1	1	2	M2	M1	1	2	M2	M1	1	2	M2
M3	3	4	M4	M3	3	4	M4	M3	3	4	M4
M5	5	6	M6	M5	5	6	M6	M5	5	6	M6
M7	7	8	M8	M7	7	8	M8	M7	7	8	M8
M9	9	10	M10	M9	9	10	M10	M9	9	10	M10
M11	11	12	M12	M11	11	12	M12	M11	11	12	M12
M13	13	14	M14	M13	13	14	M14	M13	13	14	M14
M15	15	16	M16	M15	15	16	M16	M15	15	16	M16
M17	17	18	M18	M17	17	18	M18	M17	17	18	M18
M19	19	20	M20	M19	19	20	M20	M19	19	20	M20
M21	21	22	M22	M21	21	22	M22	M21	21	22	M22
M23	23	24	M24	M23	23	24	M24	M23	23	24	M24
M25	25	26	M26	M25	25	26	M26	M25	25	26	M26
M27	27	28	M28	M27	27	28	M28	M27	27	28	M28
M29	29	30	M30	M29	29	30	M30	M29	29	30	M30
M31	31	32	M32	M31	31	32	M32	M31	31	32	M32
M33	33	34	M34	M33	33	34	M34	M33	33	34	M34
M35	35	36	M36	M35	35	36	M36	M35	35	36	M36
M37	37	38	M38	M37	37	38	M38	M37	37	38	M38
M39	39	40	M40	M39	39	40	M40	M39	39	40	M40
M41	41	42	M42	M41	41	42	M42	M41	41	42	M42
M43	43	44	M44	M43	43	44	M44	M43	43	44	M44
M45	45	46	M46	M45	45	46	M46	M45	45	46	M46
M47	47	48	M48	M47	47	48	M48	M47	47	48	M48
M49	49	50	M50	M49	49	50	M50	M49	49	50	M50
M51	51	52	M52	M51	51	52	M52	M51	51	52	M52
M53	53	54	M54	M53	53	54	M54	M53	53	54	M54
M55	55	56	M56	M55	55	56	M56	M55	55	56	M56
M57	57	58	M58	M57	57	58	M58	M57	57	58	M58
M59	59	60	M60	M59	59	60	M60	M59	59	60	M60

NI-ELVIS Interface

The NI-ELVIS interface consists of a PCI style connector located at J1 and 3 dual-row socket headers. Connector J1 connects the MCU Project Board - 2 directly to the NI-ELVIS workstation. All NI-ELVIS signals are routed to a signal breakout connector conveniently located adjacent to the breadboard. Refer to the NI-ELVIS User Guide for details on the functioning of the NI-ELVIS platform. In the figure below, all ‘B’ pins are on the top layer of the project board and all ‘A’ pins are on the bottom layer of the project board.

Figure 16: Edge Connector – J1

+15 V	A1	B1	-15 V	SCAN CLK	A32	B32	PFI 1
+15 V	A2	B2	-15 V	TRIGGER	A33	B33	CTR1_SOURCE
5V_In	A3	B3	GND	CTR1_GATE	A34	B34	CTR1_OUT
5V_In	A4	B4	GND	CTR0_SOURCE	A35	B35	CTR0_GATE
5V_In	A5	B5	GND	CR0_OUT	A36	B36	FREQ_OUT
GND	A6	B6	GND	GND	A37	B37	GND
DO 6	A7	B7	DO 7	VOLTAGE HI	A38	B38	VOLTAGE LO
DO 4	A8	B8	DO 5	AIGND	A39	B39	AIGND
DO 2	A9	B9	DO 3	ACH7+	A40	B40	ACH7-
DO 0	A10	B10	DO 1	ACH6+	A41	B41	ACH6-
GND	A11	B11	GND	ACH5+	A42	B42	ACH5-
PCI KEYWAY	A12	B12	PCI KEYWAY	ACH4+	A43	B43	ACH4-
PCI KEYWAY	A13	B13	PCI KEYWAY	AIGND	A44	B44	AIGND
DI 6	A14	B14	DI 7	ACH3+	A45	B45	ACH3-
DI 4	A15	B15	DI 5	ACH2+	A46	B46	ACH2-
DI 2	A16	B16	DI 3	ACH1+	A47	B47	ACH1-
DI 0	A17	B17	DI 1	ACH0+	A48	B48	ACH0-
GND	A18	B18	GND	AISENSE	A49	B49	N/C
GND	A19	B19	GND	PCI KEYWAY	A50	B50	PCI KEYWAY
GND	A20	B20	GND	PCI KEYWAY	A51	B51	PCI KEYWAY
GND	A21	B21	GND	N/C	A52	B52	N/C
CONN_5V	A22	B22	GND	SYNC OUT	A53	B53	FM IN
GND	A23	B23	GND	FUNC OUT	A54	B54	AM IN
N/C	A24	B24	ADDRESS 3	GND	A55	B55	CONN_5V
ADDRESS 2	A25	B25	ADDRESS 1	N/C	A56	B56	GND
ADDRESS 0	A26	B26	GLB_RESET*	CURRENT LO	A57	B57	N/C
LATCH*	A27	B27	RD_ENABLE*	3-WIRE	A58	B58	CURRENT HI
WR_ENABLE*	A28	B28	CONN_5V	N/C	A59	B59	N/C
Proto Board Present	A29	B29	PFI 6	DAC0_2	A60	B60	DAC 1
PFI 5	A30	B30	PFI 7	GND	A61	B61	GND
PFI 2	A31	B31	RESERVED	SUPPLY-	A62	B62	SUPPLY+

Signal Breakout

The following chart shows the signal breakout for the NI-ELVIS signals. These connectors are arranged from left to right above the breadboard. All signals are grouped by function and arranged to provide convenient access to the breadboard. Each signal group is labeled to ease signal identification and location. To ease prototyping, each signal is routed to two socket locations. This allows the user to easily route each to signal to multiple locations if desired. The table below details the NI-ELVS signal breakout connectors.

Figure 17: NI-ELVIS Signal Breakout – J2, J3, J4

J2

1	2	SUPPLY+	
3	4	GND	
5	6	SUPPLY-	
7	8	DAC0	ANA OUT
9	10	DAC 1	
11	12	3-WIRE	DMM
13	14	CURRENT HI	
15	16	CURRENT LO	
17	18	VOLTAGE HI	
19	20	VOLTAGE LO	
21	22	AM IN	Func Gen
23	24	FM IN	
25	26	FUNC OUT	
27	28	SYNC OUT	
29	30	CH A+	O-Scope
31	32	CH A-	
33	34	CH B+	
35	36	CH B-	
37	38	TRIGGER	
39	40	AISENSE	Analog Input
41	42	AIGND	
43	44	ACH0+	
45	46	ACH0-	
47	48	ACH1+	
49	50	ACH1-	
51	52	ACH2+	
53	54	ACH2-	
55	56	ACH3+	
57	58	ACH3-	
59	60	ACH4+	

J3

1	2	ACH4-	Analog
3	4	ACH5+	
5	6	ACH5-	
7	8	FREQ_OUT	Counters
9	10	CTR0_SOURCE	
11	12	CTR0_GATE	
13	14	CTR0_OUT	
15	16	CTR1_SOURCE	
17	18	CTR1_GATE	
19	20	CTR1_OUT	
21	22	5 V	
23	24	5 V	
25	26	RESERVED	
27	28	SCAN CLK	Programmable Function I/O
29	30	PFI 1	
31	32	PFI 2	
33	34	PFI 5	
35	36	PFI 6	
37	38	PFI 7	
39	40	3.3 V	

J4

1	2	3.3 V	
3	4	WR_ENABLE*	Digital I/O
5	6	RD_ENABLE*	
7	8	LATCH*	
9	10	GLB_RESET*	
11	12	ADDRESS 0	
13	14	ADDRESS 1	
15	16	ADDRESS 2	
17	18	ADDRESS 3	
19	20	VDD	
21	22	VDD	
23	24	DO 0	
25	26	DO 1	
27	28	DO 2	
29	30	DO 3	
31	32	DO 4	
33	34	DO 5	
35	36	DO 6	
37	38	DO 7	
39	40	GND	
41	42	DI 0	
43	44	DI 1	
45	46	DI 2	
47	48	DI 3	
49	50	DI 4	
51	52	DI 5	
53	54	DI 6	
55	56	DI 7	
57	58	+15 V	
59	60	-15 V	

TROUBLESHOOTING TIPS

The following is a list of useful problem resolution tips to try before contacting Technical Support for assistance. If the MCU Project Board - 2 still fails to operate properly, contact Axiom Manufacturing at Support@axman.com.

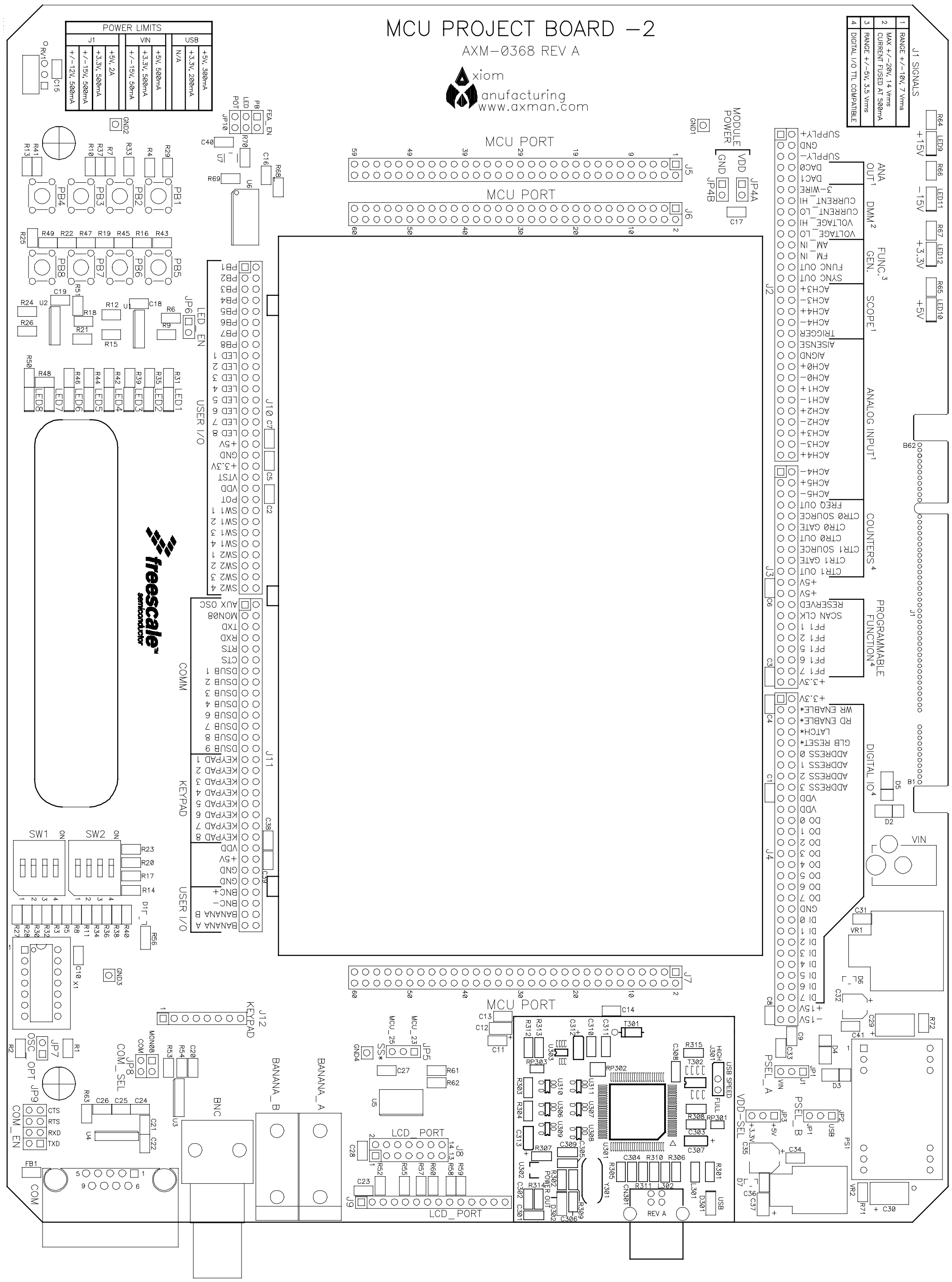
LED's on the MCU Project Board - 2 don't light
- Ensure LED_EN jumper is installed
- Make sure JP1, PWR_SEL is set to source power from the appropriate source
- Verify input power is available
- If the transformer is connected to a power strip, make sure the power strip is turned on.
- Ensure 5VDC between pins VR1-2 and VR1-3
- Measure 3.3VDC between pins VR2-2 and VR2-3

LED's on the MCU Development Module don't light
- Make sure the module is properly connected to the MCU Project Board - 2
- Make sure a power cord is not connected to the module
- Make sure the MODULE POWER option jumpers are installed
- Make sure the PWR_SEL option header on the Development Module is setup properly

No Prompt at the AxIDE Terminal
- Make sure the Serial cable is connected to the HOST PC
- Make sure the correct serial port is selected in the AxIDE program
- Make sure the AxIDE program options setting are configured correctly

APPENDIX A

SILKSCREEN



APPENDIX B

Bill of Materials

Item	Qty	Title		Mfr	Mfr P/N
1	2	Cap, Tant, 15uF, 35V, D Case	C29, C30	Kemet	T491D156K035AS
2	2	Cap, Tant, 10uF, 10V, 10%, SMA	C12, C307	Avx	TAJA106K010R
3	2	Cap, Tant, 4.7uF, 16V, SMA	C312, C313	Kemet	T491A475M016AS
4	0	**Cross to 4.7uF, 16V, SMA above**		Nichicon	F931C475MAA
5	1	Cap, Tant, 2.2uF, 10V, 10%, A case	C37	Kemet	T491A225K010AS
6	1	Cap, Elec, 100uF, 16V, 20%, 6.3x5.4, SMT	C35	Nichicon	UWT1C101MCL1GB
7	1	Cap, Elec, 22uF, 16V, 20%, 5.3x5.4, SMT	C32	Nichicon	UWX1C220MCL1GB
8	1	Cap, 1000pF, 50V, X7R, 0805	C302		
9	3	Cap, .01uF, 50V, X7R, 0805	C13, C43, C311		
10	1	Cap, .47uF, 16V, Y5V, 0805	C31	Panasonic	ECJ-2VF1C474Z
11	41	Cap, .1uF, 50V, X7R, 0805	C1, C2, C3, C4, C5, C6, C7, C8, C9, C10, C11, C14, C15, C16, C17, C18, C19, C20, C21, C22, C23, C24 ,C25, C26, C27, C28, C33, C34, C36, C38, C39, C40, C41, C42, C43, C301, C303, C304, C308, C309, C310		
12	2	Cap, 22pF, 50V, 5%, NPO/COG, 0805	C305, C306		
13	1	Res, 4.22K ohm, 1%, 0805	R74		
14	1	Res, 820 ohm, 1%, 0805	R75		
15	1	Res, 120 ohm, 1%, 0805	R2		
16	1	Res, 68.1 ohm, 1%, 0805	R1		
17	2	Res, 33.0 ohm, 1%, 0805	R310, R311	Yageo	9C08052A33R0FKHFT
18	1	Res, 1M ohm, 5%, 1/4W, 0805	R309		
19	33	Res, 10K ohm, 5%, 0805	R3, R4, R5, R6, R7, R8, R9, R10, R11, R12, R13, R14, R15, R16, R17, R18, R19, R20, R21, R22, R23, R24, R25, R26, R51, R57, R58, R59, R60, R61, R62, R63, R303		
20	6	Res, 4.7K ohm, 5%, 0805	R53, R54 ,R68, R69, R70, R73		

21	2	Res, 3K ohm, 5%, 0805	R71, R72		
22	2	Res, 2.8K ohm, 5%, 0805	R64, R66		
23	2	Res, 1.5K ohm, 5%, 0805	R304, R305		
24	10	Res, 1K ohm, 5%, 0805	R29, R33, R37, R41, R43, R45, R47, R49 R307, R314		
25	12	Res, 100 ohm, 5%, 0805	R27, R28, R30, R32, R34, R36, R38, R40, R52, R76, R77, R78		
26	1	Res, 680 ohm, 5%, 1206	R56		
27	11	Res, 680 ohm, 5%, 0805	R31, R35, R39, R42, R44, R46, R48, R50, R65, R301, R302		
28	2	Res, 510 ohm, 5%, 0805	R306, R308		
29	1	Res, 270 ohm, 5%, 0805	R67		
30	2	Res, 47 ohm, 5%, 0805	R312, R313		
31	1	Res, 0 ohm, 5%, 0805	R55		
32	1	Res, Ntwk, 10K ohm, Iso, 8P4R, SMD	RP302	CTS	742C083103J
33	2	Res, Ntwk, 10K ohm, Iso, 4P2R, SMD	RP301, RP303	CTS	742C043103J
34	1	Res, Variable, 5K ohm, .5W, 3/8 vert adj. W/ knob	RV1	Bourns	3352W-1-502
35	3	IC, Buf, Hex, 3S, 74ACT125, 14SOIC	U1, U2, U3	On Semi	MC74ACT125DR2
36	1	IC, XCVR, Dual RS232, 3.3V-5.0v, 16 SOIC	U4	Intersil	ICL3232ECBN
37	1	IC, 8b Shift Reg, Latch, 3S, 74HC595, 16 SOIC	U5	TI	SN74HC595D
38	1	IC, Octal FET Bus Sw, 20SOIC	U6	TI	SN74CBT3244DWR
39	4	IC, Bilateral Analog Sw, 1G, SOT23-5	U7, U306, U309, U310	TI	SN74LVC1G66DBVR
40	1	IC, LV Reset, 5V, 8SOIC	T302	On Semi	MC34164D-5R2
41	1	IC, MCU, MC9S12UF32PU, Programmed, 100TQFP	U301	P&E	UF32-MCUSLK
42	1	Trans, MOSFET, P-Ch, -20V, -3.7A, SOT-23	U302	IR	IRLML6402TR
43	1	Tran, NPN, 40V, 200mA, SOT23	Q1	Fairchild	MMBT3904
44	1	Tran, PNP, -40V, -200mA, SOT23	Q2	Fairchild	MMBT3906
45	1	IC, Buf, Dual, 3-S, 8SSOP	U303	TI	SN74LVC2G125DCTR
46	1	IC, COMP, R-R, SOT23-5	U307	National	LMV7219M5
47	2	IC, Comp, R-R, SOT23-5	U308, U311	National	LMV7239M5
48	0	IC, Analog Sw, Bilateral, Dual, SSOP	DELETED	TI	SN74LVC2G66DCT
49	1	Diode, Zener, 5.6V, .5W, DO-35, thru	T301	Fairchild	1N752A
50	1	Diode, Zener, 8.2V, 200mW, SOT23	D1	Diodes	MMBZ5237BW-7
51	4	Diode, Rect, S1A, 1A, 50V, DO214AC	D2, D3, D4, D5	Vishay	S1A

52	2	Diode, Schottky, 30V, 200mA, BAT54C, Com. Cathode, SOT23	D6, D7	General Sem.	
53	13	LED, Green, w/reflector, 1206, SMT	LED1, LED2, LED3, LED4, LED5, LED6, LED7, LED8, LED9, LED10, LED11, LED12, D301	Rohm	SML-010MTT86
54	1	LED, Yellow, w/reflector, 1206, SMT	D302	Rohm	SML-010YTT86
55	1	Ind, Ferrite, EMI, 330 ohm @ 100 MHz, 1.5A, 0805	FB1	Mouser	81-BLM21P331SG
56	2	Ind, Ferrite , EMI, 1.5A, 26 ohm, 1206, SMD	L301, L302	Steward	MI1206K260R-00
57	1	Pwr Sup, SW, +5Vin, +/-15Vout, 50mA, Qtr Brick	PS1	Cincon	EC2A05N
58	1	VReg, LDO, 5.0V, 1000mA,TO-263	VR1	National	LM2940S-5.0
59	1	VReg, LDO, 3.3V, 500mA, TO-263	VR2	National	LM2937ES-3.3
60	2	Sw, DIP, 4 pos, SPST, SMT	SW1, SW2	CTS	219-4MST
61	8	Sw, PB, 5mm Sq, thru	PB1, PB2, PB3, PB4, PB5, PB6, PB7, PB8	E-Switch	EG1827
62	1	XTAL, 12.000 MHz, SMT, 18PF	Y301	Citizen	HCM49-12.000MABJT
63	1	Socket, IC, 14P DIP, .3", thru	X1		
64	1	Hdw, Heatsink, Thermalloy, T0-263	VR1	Aavid	573300D00010
65	4	Conn, 1x1, pin hdr, .1", thru	GND1, GND2, GND3, GND4		
66	5	Conn, 1x2 pin hdr, .1" Ctr, thru	JP4A, JP4B, JP6, JP7, JP11		
67	6	Conn, 1x3 pin hdr, .1" Ctr, thru	JP1, JP2, JP3, JP5, JP8, J301		
68	1	Conn, 1x8 pin hdr, .1" Ctr, thru	J12		
69	1	Conn, 2x2 pin hdr, .1" Ctr, thru	JP12		
70	0	Conn, 2x3 pin hdr, .1" ctr, thru	DELETED		
71	1	Conn, 2x4 pin hdr, .1" Ctr, thru	JP9, JP10		
72	2	Conn, 2x7 pin hdr, .1" Ctr, thru	J8		
73	1	Conn, Hdr, Socket, 2x20, .1", thru	J3		
74	7	Conn, Hdr, Socket, 2x30, .1", thru	J2, J4, J5, J6, J7, J10, J11		
75	1	Conn, 2.1mm, Pwr Jack, Barrel, thru, RA	VIN		
76	1	Conn, Sckt, USB, Type B, Horiz, thru	CN301	Keystone	924K
77	1	Conn, Dsub, 9P, F, RA, PCB Mount	COM		
78	1	Conn, Spec, BNC, RA w/ mtg posts, Black, PCB, thru	BNC	Amp/Tyco	227161-2
79	1	Conn, Recpt, Banana, 4.0 mm, Black, thru	Banana B	Deltron	164-6218
80	1	Conn, Recpt, Banana, 4.0 mm, Red, thru	Banana A	Deltron	164-6219
81	1	Buzzer, Mag, 2.3kHz, 5V, PCB mount, thru	BZ1	Soberton	WT-1205

82	18	Hdw, Shunt, 2 Pos, .1"	JP1, JP2, JP3, JP4A, JP4B, JP5, JP6, JP7, JP8(2), JP9(4), JP10(3), J301		
83	8	Hdw. Rubber Bumper, .45"x.2", Hemisphere			
84	2	Hdw, Protoboard, 5.7"x1.8", 550 pt		E-Call	165-40-7010
85	1	PCB, MCU Project Board-2, 8.5" x 11.0", 2 Layer			
86		**ASSEMBLY**			
87	1	Assy, PCB, CSM-12C32		Axiom	AXM-0332
88	1	Assy, CE Power Supply, 9V,		Mouser	418-TR10R090
89	1	Assy, Cbl, Serial, 6', DB9F-DB9M			
90	1	Assy, Cbl, USB, 6', A/B		Kobiconn	172-1024
91	10	Wire, Jumper, Bl, 9", both ends stripped, bent			
92	25	Wire, Jumper, Or, 3", both ends stripped, bent			
93	1	Media, Support CD, MCU Project			
94	1	Doc, User Guide, Printed		Axiom	DOC-0368-010
95	1	Foam Set			
96	1	Shipping box			
97		**DO NOT INSTALL COMPONENTS**			
98	0	Conn, 1x14 pin hdr, .1" Ctr, thru	J9		
99	0	Res, 1.5K ohm, 5%, 0805	R315		
100	2	Conn, 2x7 pin hdr, .1" Ctr, thru	J13		